

/ Descriptions

1000V 1.0A SMA

Surface Mount Superfast Recovery Rectifier,Reverse Voltage:1000V,Forward Current:1.0A, SMA package.

/ Features

RoHS 2011/65/EU

Glass Passivated Chip Junction Superfast reverse recovery time Lead free in comply with EU RCHS 2011/65/EU directives For surface mounted applications,HF product.

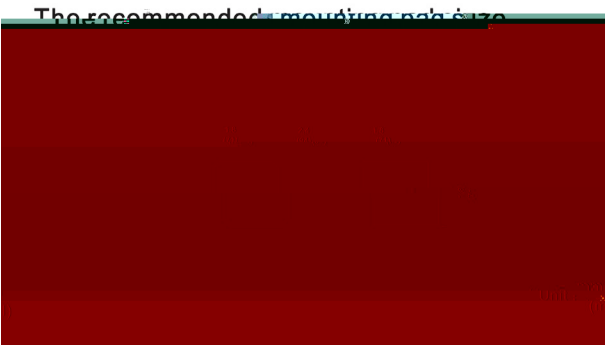
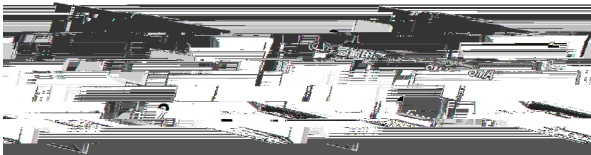
/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

/ Marking

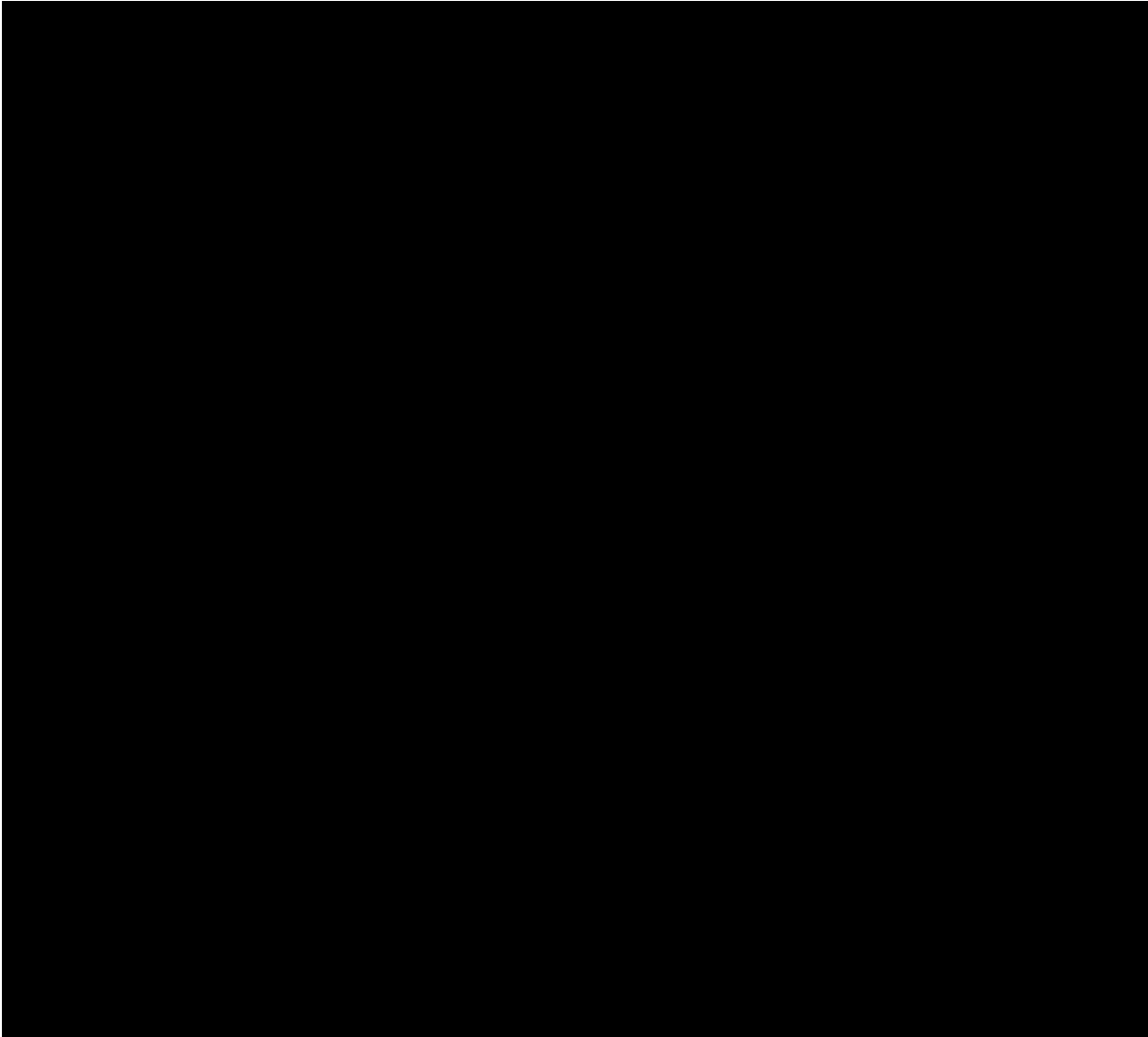
See Marking Instructions.

Parameter	Symbol	Rating	Unit
		ES1M	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current	$I_{F AV}$	1.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30	A
Typical Junction Capacitance at $V_R = 4V, f = 1MHz$	C_j	20	pF
Typical Thermal Resistance ¹	R_{JA}	75	/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150	

Note:

1 P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 cm) copper pad areas.

/ Package Dimensions



/ Marking Instructions



ES1M

Note:

ES1M Product Type Code

**** Lot No. Code, code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- | | | | | | |
|---|-------|-----|----|-----------|---------------------------------------------|
| | | | | | |
| 1 | 150 | 180 | 60 | 90sec; | Note: 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec
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